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Date: August 16, 2002

*Joseph R. Keating*  
Joseph R. Keating

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*Draftsman*  
*DEVANS*  
*8-30-02*

PATENT  
36856.345

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant: Masaya WAJIMA et al.

Serial No.: 09/656,106

Filed: September 6, 2000

Title: CHIP ELECTRONIC COMPONENT  
AND MOUNTING STRUCTURE OF THE  
SAME

Art Unit: 2834

Examiner: J. Gonzalez

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**REQUEST FOR APPROVAL OF PROPOSED DRAWING CORRECTION**

Assistant Commissioner for Patents  
Washington, D.C. 20231

Sir:

Applicants respectfully request review and approval of the proposed drawing corrections contained on the attached drawing sheet. Fig. 2 has been amended in the attached drawing sheet to show the recesses in the first and second case substrates as required by the Examiner. The corrections to Fig. 2 do not add any new matter as the recesses in the first and second case substrates were described in the originally filed specification and recited in the originally filed claims. Accordingly, Applicants respectfully request consideration and entry of the corrections to Fig. 2.

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Upon the indication of allowable subject matter, Applicants will submit a formal drawing sheet for Fig. 2 including the corrections attached hereto.

Respectfully submitted,

Date: August 16, 2002

  
Attorneys for Applicant

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